

SOLDERING AND DESOLDERING MACHINE SSM 4, SSM 4A AND SSM 9

MACHINES

1.107



APPLICATION: Through-hole

ZEVAC line: SSM

The complete SSM product line documentation is composed of the following data sheets:

MACHINES 1.107

ACCESSORIES 1.201

OPTIONS 1.301



APPLICATION RANGE

SELECTIVE SOLDERING AND DESOLDERING OF MULTILEAD COMPONENTS. THE SOLDERING AND DESOLDERING MACHINES OF THE SSM LINE ARE IDEAL FOR:

Repairs

Defective components can be removed and new components soldered in place.

Prototyping

Prototypes can be equipped and soldered in an efficient way with the SSM 4 and SSM 9.

Retrofits

Components which are missing at production time.

On the soldering side components have to be placed.

A SMD equipped board has to be extended by single wired components.

Soldering

When equipping boards with only few components the use of the soldering and desoldering machines SSM 4 or SSM 9 is in most cases the simplest and most economical way.

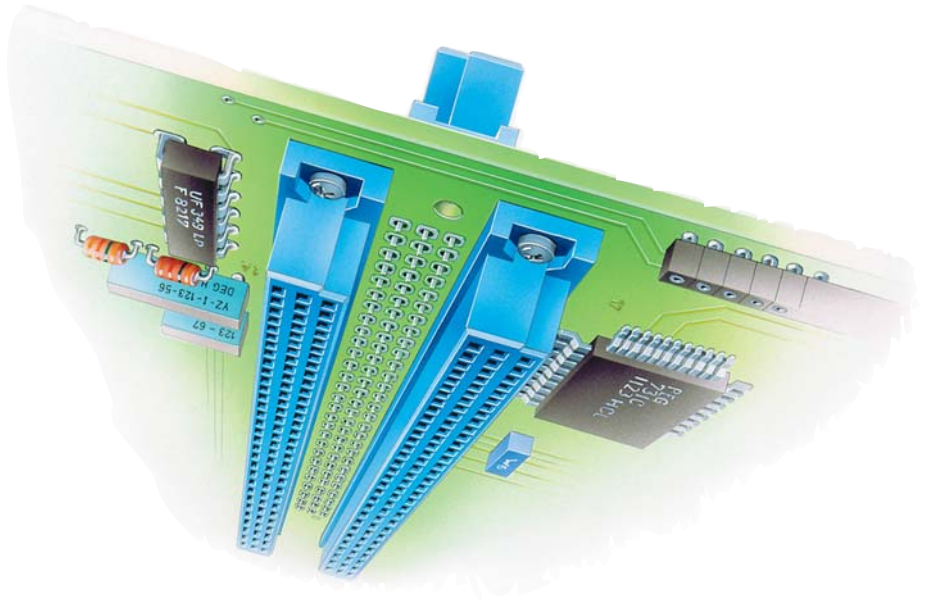
Saves time

The system's ergonomic design speeds up and simplifies your work and generates results that comply with the most stringent quality requirements.

No Restrictions

The SSM 4 and SSM 9 will dependably handle even the most difficult soldering and desoldering jobs:

- Operations on multilayer boards
- Processes components with complex geometries such as DIP switches and long connectors
- Operates on dense mixed-technology boards
- Soldering on the assembly side, even between adjacent high components
- Soldering and desoldering of Pin Grid Arrays and sockets
- Soldering on flex boards



MARKET REQUIREMENT

INCREASED SOPHISTICATION AND FAST DEVELOPING SMT HAS GENERATED AN URGENT NEED FOR A TRULY PROFESSIONAL SOLUTION TO SOLDER AND DESOLDER COMPONENTS OF THE THROUGH-HOLE TECHNIC IN A PROFESSIONAL WAY. FOR SELECTIVE SOLDERING AND DESOLDERING OF CONNECTORS AND OTHER HIGH QUALITY MULTIPOLAR COMPONENTS. SSM 4 AND SSM 9 MEET THESE REQUIREMENTS IN A PARTICULAR WAY.

Enhanced effectiveness

- Fast positioning with the air nozzle.
- Soldering and desoldering at the same time/position.
- Reliable blow-out of solder holes from above, immediately after removal of the device.

Enhanced quality

- Precise adjustment of soldering parameters
- Reproducible results
- Non mechanical stress protects device and circuit board against damage
- Adjacent devices are protected during soldering process. Heat is isolated to a single component.

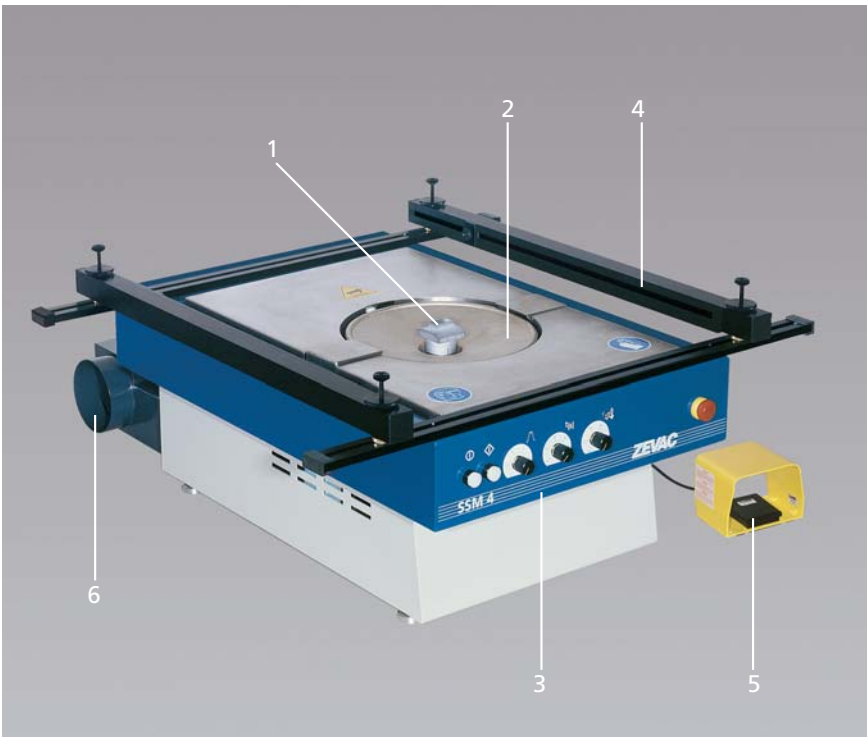
PREHEATER MODULE PH4

Option for SSM 4A and SSM 9

The preheater module PH4 is required for the preheating of printed circuit board before starting the selective soldering process, especially for lead-free applications.

The preheater PH4 with an IR radiation area of 300x300mm and a thermal output of 3500W is a standalone unit and can be operated together with any SSM 4A or SSM 9 machine.

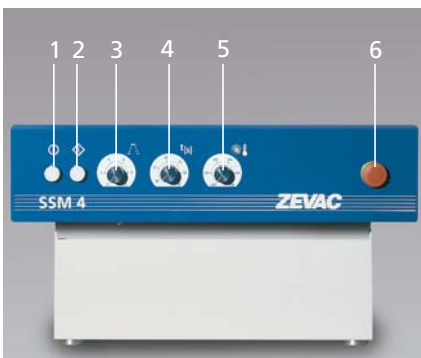




SSM 4:

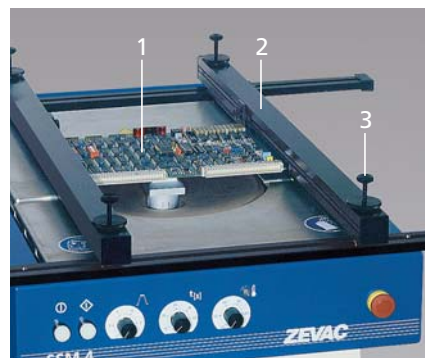
Unique in performance and design:

- 1 Flow well
- 2 Solder pot
- 3 Control panel
- 4 Print holder
- 5 Footswitch (Option)
- 6 Fume extraction system (Option)



Control panel:
Clearly arranged operation and control

- 1 Main switch ON/OFF
- 2 Cycle switch
- 3 Solder wave height
- 4 Solder wave duration
- 5 Temperature control
- 6 Emergency switch



Print holder:
For easy positioning

- 1 Printed Circuit Board
- 2 Print holder
- 3 Height adjustment for board carrier

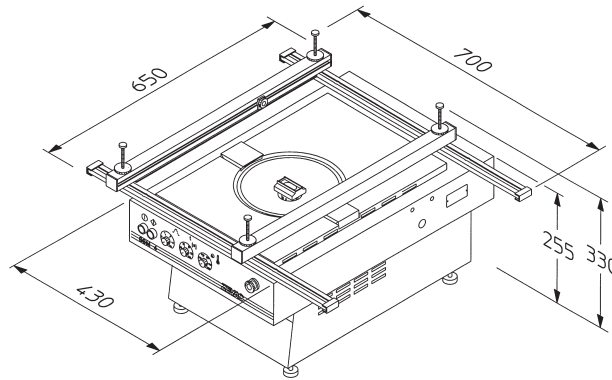


Flow well:
Safe soldering and desoldering

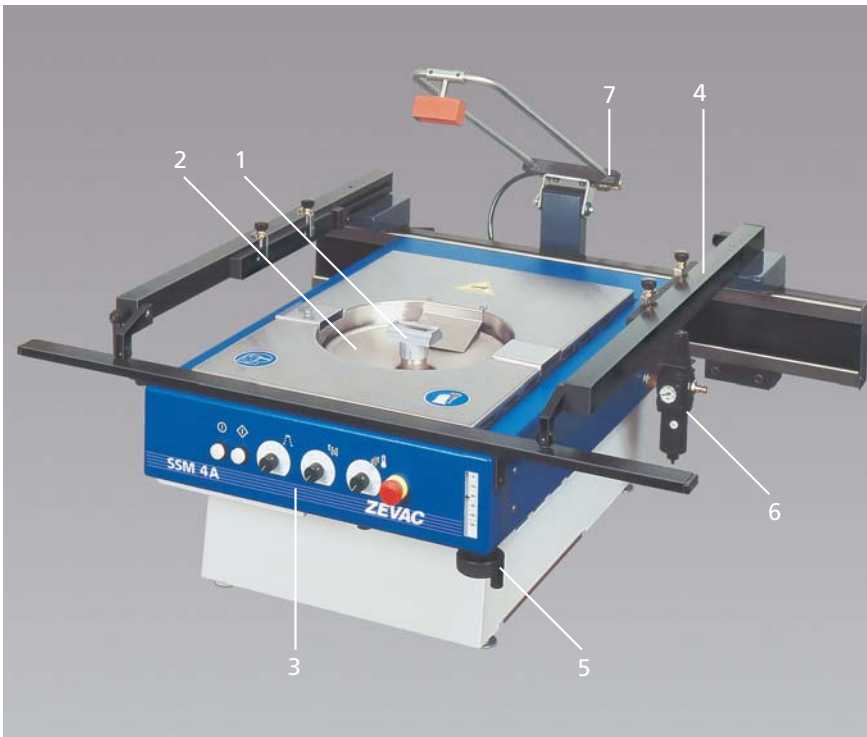
Independent parameters, reduces operator error for reproducible results.

Technical data	Product designation	SSM 4
	Max. board size	600 x 600 mm
	Pumping system	solder pump
	Heat up time	approx. 30 min.
	Cycle duration	0 - 60 s
	Air pressure	1 - 8 bar
	Solder temperature	200° C - 300° C
	Max. power consumption	2500 Watt
	Power requirements	220 - 230 Volt, 50 Hz
	Dimensions (L x W x H)	440 x 800 x 360 mm
	Solder content	approx. 16 kg
Weight (without solder)	47 kg	
Technical data subject to change		

Dimensions



Accessories and options	Flow wells and cleaning hoods	Data sheet 1.201
	Print holder	Order no. 204.023.000
	Footswitch	Order no. 249.000.708
	Blow-out system	Order no. 204.032.000
	Solder pot cover, round	Order no. 204.033.000
	Fume extraction system	Order no. 209.034.000



SSM 4A:

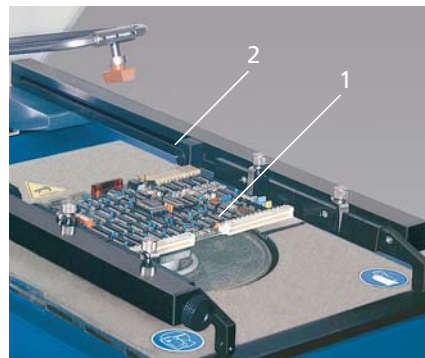
Unique in performance and design:

- 1 Flow well
- 2 Solder pot
- 3 Control panel
- 4 Print holder
- 5 Height adjustment for board carrier
- 6 Connection for optional blow-out system
- 7 Blow-out system (option)



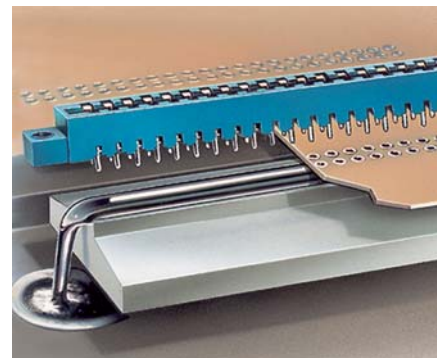
Control panel:
Clearly arranged operation and control

- 1 Main switch ON/OFF
- 2 Cycle switch
- 3 Solder wave height
- 4 Solder wave duration
- 5 Temperature control
- 6 Emergency switch



Print holder:
For easy positioning

- 1 Printed Circuit Board
- 2 Print holder

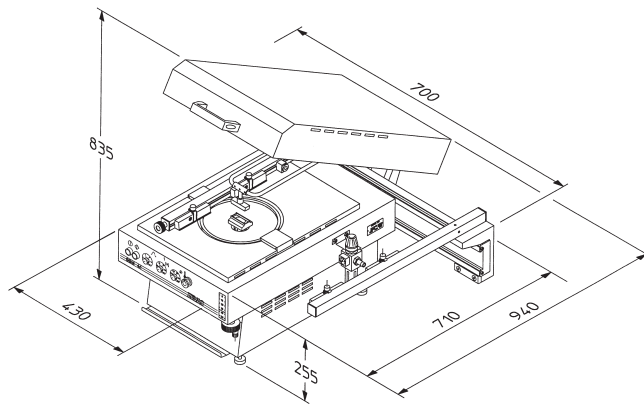


Flow well:
Safe soldering and desoldering

Independent parameters, reduces operator error for reproducible results.

Technical data	Product designation	SSM 4A
	Max. board size	600 x 600 mm
	Pumping system	solder pump
	Heat up time	approx. 30 min.
	Cycle duration	0 - 60 s
	Air pressure	1 - 8 bar
	Solder temperature	200° C - 300° C
	Max. power consumption	2500 Watt
	Power requirements	220 - 230 Volt, 50 Hz
	Dimensions (L x W x H)	440 x 800 x 360 mm
	Solder content	approx. 16 kg
Weight (without solder)	47 kg	
Technical data subject to change		

Dimensions



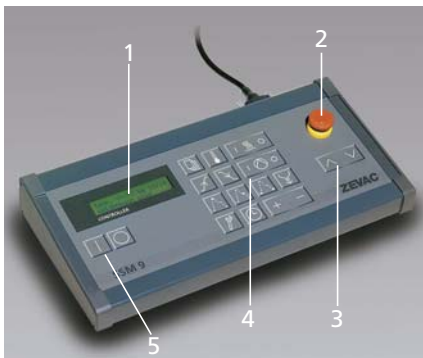
Accessories and options	Flow wells and cleaning hoods	Data sheet 1.201
	Print holder support	Order no. 209.025.000
	Single footswitch	Order no. 249.000.708
	Double footswitch	Order no. 249.000.743
	Blow-out system	Order no. 204.032.000
	Solder pot cover, round	Order no. 209.033.002 B
	Fume extraction manifold	Order no. 2209.034.000
	IR preheater PH4 SSM	Order no. 206.002.000
	Machine cover	Order no. 209.033.000 Order no. 209.035.000



SSM 9:

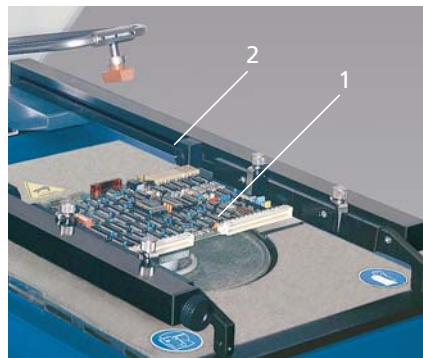
Unique in performance and design:

- 1 Flow well
- 2 Cleaning hood
- 3 Fume extraction system (Option)
- 4 Control panel
- 5 Board carrier
- 6 Board carrier height adjustment
- 7 Locking of board carrier
- 8 Footswitch
- 9 Machine cover (Option)
- 10 Solder pot



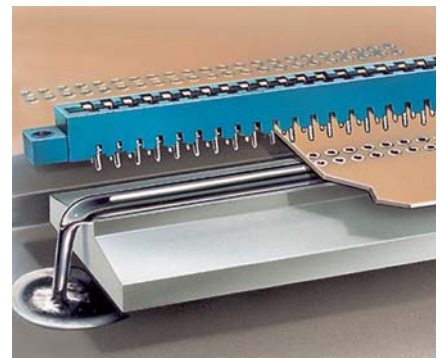
Control panel:
Clearly arranged operation and control

- 1 Display
- 2 Emergency switch
- 3 Motorized Z-axis (Option)
- 4 Input (Foil keyboard)
- 5 ON/OFF switch



Board carrier:
For easy positioning

- 1 Printed Circuit Board
- 2 Board carrier

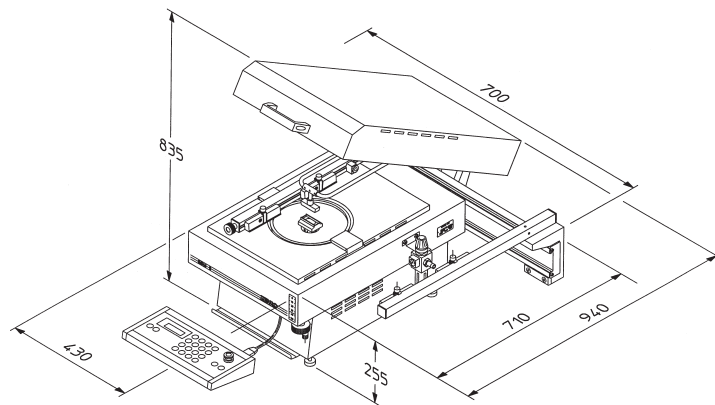


Flow well:
Safe soldering and desoldering

Independent parameters, reduces operator error for reproducible results.

Technical data	Product designation	SSM 9
	Max. board size	840 x 600 mm
	Pumping system	solder pump
	Heat up time	approx. 30 min.
	Cycle duration	0 - 60 s
	Air pressure	1 - 8 bar
	Solder temperature	235° C - 400° C
	Max. power consumption	2500 Watt
	Power requirements	220 - 230 Volt, 50 Hz
	Dimensions (L x W x H)	440 x 800 x 360 mm
	Solder content	approx. 16 kg
	Weight (without solder)	75 kg
Technical data subject to change		

Dimensions



Accessories and options	Flow wells and cleaning hoods	Data sheet 1.201
	Print holder support	Order no. 209.025.000
	Single footswitch	Order no. 249.000.708
	Double footswitch	Order no. 249.000.743
	Blow-out system	Order no. 209.032.000
	Solder pot cover, round	Order no. 209.033.002 B
	Fume extraction manifold	Order no. 209.034.000
	IR preheater PH4 SSM	Order no. 206.002.000
	Machine cover	Order no. 209.033.000 Order no. 209.035.000

ZEVAC Distributor

ZEVAC	ZEVAC AG	Telephone	+41 32 626 20 80
	Vogelherdstrasse 4	Fax	+41 32 626 20 90
	CH - 4500 Solothurn / Switzerland	E-mail	info@zevac.ch
		Website	www.zevac.ch